

IN THE CLAIMS:

Please cancel Claims 6 - 12 which are withdrawn under a restriction requirement, amend Claims 1 - 6, and add new Claims 13 - 18 as follows.

1. (Once Amended / Currently Amended) A ~~substrate~~ process chamber component used in the production of semiconductor devices comprising:

at least one internal component ~~formed from~~ including an anodized aluminum alloy surface; and

a spray-coated yttrium oxide coating ~~formed on~~ overlying a the anodized aluminum surface of the at least one internal component, said coating having a mechanically finished surface essentially free from loose particles.

2. (Once Amended / Currently Amended) A ~~substrate~~ process chamber component as in accordance with claim 1, and wherein the at least one internal component is a chamber liner.

3. (Once Amended / Currently Amended) A ~~substrate~~ process chamber component as in accordance with claim 1, and wherein the at least one internal component is a cathode liner.

4. (Once Amended / Currently Amended) A ~~substrate~~ process chamber component as in accordance with claim 1, and wherein the at least one internal component comprises a chamber door.

5. (Once Amended / Currently Amended) A ~~substrate~~ process chamber component as in accordance with claim 1, and wherein the anodized aluminum alloy comprises anodized high purity aluminum alloy.

6 - 12. (Cancelled in view of withdrawal under a restriction requirement)

13. (New) A processing chamber component resistant to a plasma including fluorine and oxygen species, said component comprising:

a high purity aluminum substrate where particulates formed from mobile impurities have a particle size distribution such that no more than 0.2 % of the particles are larger than 20 μm , with no particles being larger than 50 μm ;

an anodized coating on a surface of the high purity aluminum substrate; and

a protective coating comprising yttrium oxide overlying the anodized coating.

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14. (New) A processing chamber component in accordance with claim 13, wherein said high purity aluminum substrate particle size distribution with respect to particulates formed from mobile impurities is such that at least 95 % of all particles must be less than 5 μm in size, with no more than 0.1 % of the particles being larger than 20 μm , and with no particles being larger than 40 μm .

15. (New) A processing chamber component in accordance with claim 13, wherein said protective coating includes aluminum oxide up to about 10 % by weight.

16. (New) A process chamber component in accordance with claim 13, wherein said protective coating is 99.95 % by weight or greater yttrium oxide.

17. (New) A process chamber component in accordance with claim 13, wherein said protective coating is coating applied using a method selected from the group consisting of spray coating, chemical vapor deposition, and physical vapor deposition.

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cont 18. (New) A process chamber component in accordance with claim 17, where the coating comprising yttrium oxide has been mechanically finished to remove loose particles.
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